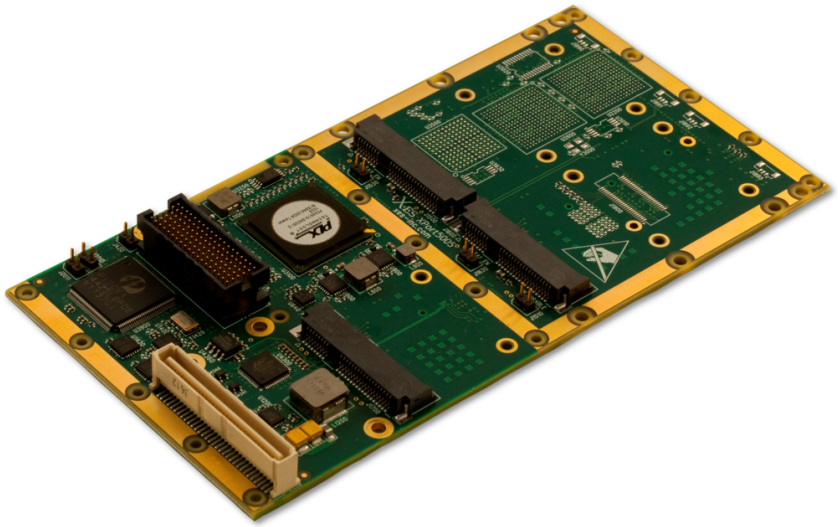
XPort5005

XMC Form Factor Mini PCI Express Card Carrier Board

- Supports up to three Mini PCI Express cards
- Conduction-or air-cooled
- Supports two Full-Height Mini-PCIe cards, two mSATA modules, or three Half-Height Mini-PCIe cards
- XMC PCIe interface
- Includes three mini-SIM card sockets
- Mini-PCIe CEM 2.0-compliant
- Each Mini-PCIe site supports USB or PCIe
- Up to two dual redundant channels of MIL-STD-1553
- Integration services with third-party modules available
- Conformal coating available



XPort5005

The XPort5005 provides rapid support for a wide array of application-specific I/O to any system that includes an XMC slot. It can be used in conduction-or air-cooled applications. By supporting up to three Mini-PCIe cards, the XPort5005 provides a flexible platform for hosting everything from wireless modules (WLAN, cellular, GPS) to communication modules (MIL-STD-1533, CAN, ARINC-429) and anything in between. The XPort5005 provides an ideal platform for providing a mezzanine that meets your applications interface requirements. The XPort5005 can operate within the demanding environments of MIL-STD-810.

The XPort5005 has sites for two Full-Height Mini-PCIe cards and a Half-Height Mini-PCIe card. All three sites support x1 PCIe 2.0 and a USB 2.0 interface for added flexibility. Each site also provides a mini-SIM socket for use with cellular modules. Alternatively, the two Full-Height Mini-PCIe sites can be populated with mSATA modules to meet your solid state storage requirements. X-ES also offers integration services for third-party modules.

X-ES
Extreme Engineering Solutions

...Always Fast

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P15 XMC Interface

- Up to x8 PCI Express port

P14 PMC Interface

- Up to two dual redundant channels of MIL-STD-1553
- Up to four channels of CAN
- Other Mini-PCIe card I/O

Configuration Options

- Two Full-Height Mini-PCIe and one Half-Height Mini-PCIe sites
- Up to two dual redundant channels of onboard MIL-STD-1553
- Front panel I/O breakout boards available

Software Support

Support based on board configuration.

- Wind River VxWorks BSP
- Linux BSP
- Microsoft Windows drivers

Physical Characteristics

- XMC conduction- or air-cooled form factor
- Dimensions: 143.75 mm x 74 mm

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration. Please consult factory.

Supported Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g²/Hz, 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing